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HEET

U.S. Department of Commerce  
Patent and Trademark Office  
Attorney Docket No. 08409.0027



102223739

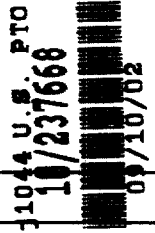
ATTN. BOX ASSIGNMENTS

To the Honorable Commissioner of F  
Please record the attached original d

1. Name of conveying party(ies):  
Jung-Yu Hsieh and Tzung-Ting Han

2. Name and address of receiving party(ies):

Name: Macronix International Co., Ltd.



Additional name(s) of conveying party(ies) attached?  Yes  No

Internal Address:

3. Nature of conveyance:

MPD  
9/10/02

Street Address: No. 16, Li-Hsin Road  
Science-Based Industrial Park  
Hsinchu, Taiwan R.O.C.

Assignment  Merger  
 Security Agreement  Change of Name

City:  
State: Zip Code:

Other:

Additional name(s) & Address(es) attached?

Execution Date: September 3, 2002

Yes  No

4. Application number(s) or patent number(s):

A. Patent Application Number(s):

10237668

B. Patent Number(s):

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Yitai Hu, Esquire

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

Street Address: 1300 I Street, N.W.

City: Washington, D.C.

State: Zip: 20005-3315

6. Total number of applications and registrations involved:  
1

7. Total fee (37 CFR 3.41): \$40

Enclosed (Please charge deficiency to deposit account)  
 Authorized to be charged to deposit account

8. Deposit Account No.: 06-0916

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Yitai Hu, Reg. No. 40,653

Signature

September 10, 2002

Total number of pages including cover sheet, attachments and documents: 2

09/11/2002 WABRHAM1 00000027 10237668

02 FC:581

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PATENT  
REEL: 013283 FRAME: 0213

**ASSIGNMENT**

WHEREAS We, the below named inventors, (hereinafter referred to as Assignors), have made an invention entitled:

**ONO INTERPOLY DIELECTRIC FOR FLASH MEMORY CELLS AND METHOD FOR FABRICATING THE SAME USING A SINGLE WAFER LOW TEMPERATURE DEPOSITION PROCESS**

for which WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS, Macronix International Co., Ltd., a corporation of Hsinchu, Taiwan, R.O.C. whose post office address is No. 16, Li-Hsin Road, Science-Based Industrial Park, Hsinchu, Taiwan, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for and in consideration of the sum of One Dollar (\$1.00) in hand paid and other good and valuable consideration the receipt of which from Assignee is hereby acknowledged, We, as Assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention, provisional application Serial No. \_\_\_\_, filed \_\_\_\_ (if any), and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional application (if any), as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that We have the full right to convey the interest assigned by this Assignment, and We have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

Jung-Yu HSIEH	JUNG-YU HSIEH	9/3/2002
FULL NAME OF FIRST INVENTOR	INVENTOR'S SIGNATURE	DATE
Tzung-Ting HAN	Tzung-Ting Han	9/3/2002
FULL NAME OF SECOND INVENTOR	INVENTOR'S SIGNATURE	DATE